



Intelligence and Automation in Construction

Guest Editors:

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Dr. Mukhtar A. Kassem

Dr. Lincoln C. Wood

Dr. Jeffrey Boon Hui Yap

Deadline for manuscript
submissions:

closed (31 August 2023)

Message from the Guest Editors

Dear Colleagues,

The special issue of “Intelligence and Automation in Construction” invites original research papers on all aspects pertaining to the use of Information Technologies in Design, Engineering, Construction Technologies, and Maintenance and Management of Constructed Facilities. The scope encompasses all stages of the construction life cycle from initial planning and design, through construction of the facility, its operation and maintenance, to the eventual dismantling and recycling of buildings and engineering structures. The following list of topics is not intended to be exhaustive, but rather to indicate topics that fall within this issue:

- Computer-aided design, product modeling, decision support systems, classification and standardization, product data interchange
- Computer-aided engineering, process simulation models, graphics
- Robotics, metrology, logistics, automated inspection, demolition/remediation
- Facilities management, management information systems, intelligent control systems.

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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